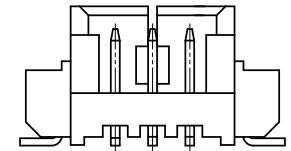
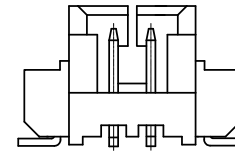
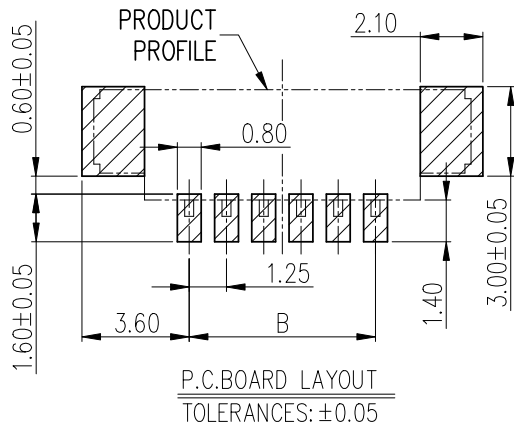
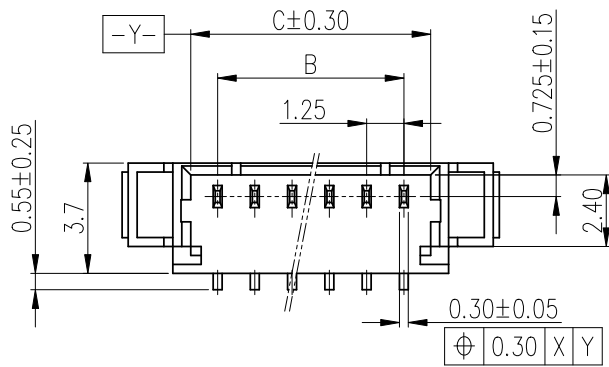


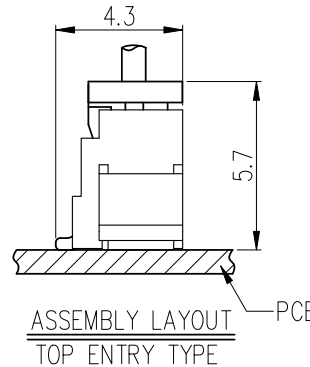
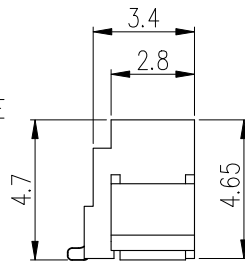
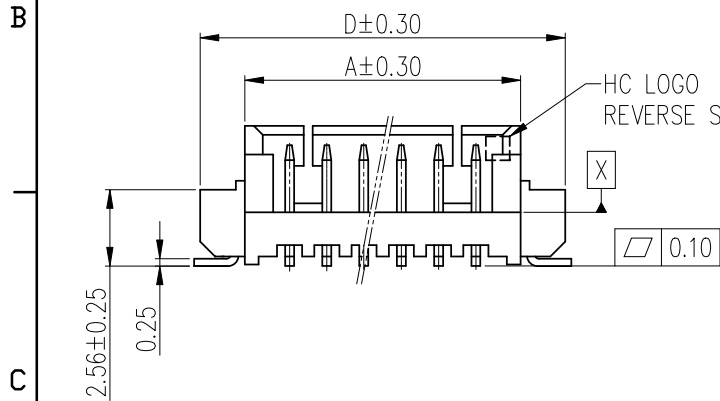
RoHS



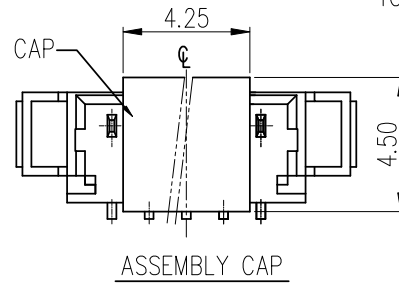
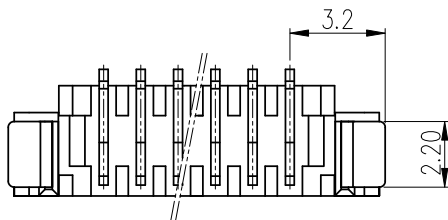
2 POS

3 POS

- MATERIAL SPECIFICATION:
 - 1.1 INSULATION: LCP UL 94V-0.
 - 1.2 CAP : LCP UL 94V-0,COLOR:NATURAL.
 - 1.3 CONTACT: THICK 0.30mm PHOSPHOR BRONZE.
 - 1.4 SOLDER TAB: THICK 0.25mm PHOSPHOR BRONZE.
- FINISH SPECIFICATION:
 - 2.1 CONTACT: MATTE TIN PLATING
 - 2.2 SOLDER TAB: MATTE TIN PLATED.
- BILL OF PART NO:
 - 1253WD-XP-AX-HC-HF
 - COLOR: BLANK=NATURAL
A=BLACK
 - NO. OF CIRCUITS: 2~10
- FOR FINISH, AVAILABILITY, DELIVERY & MOQ, CONTACT CKM
- DIMENSIONAL



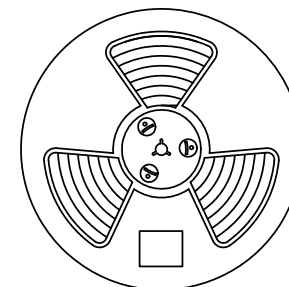
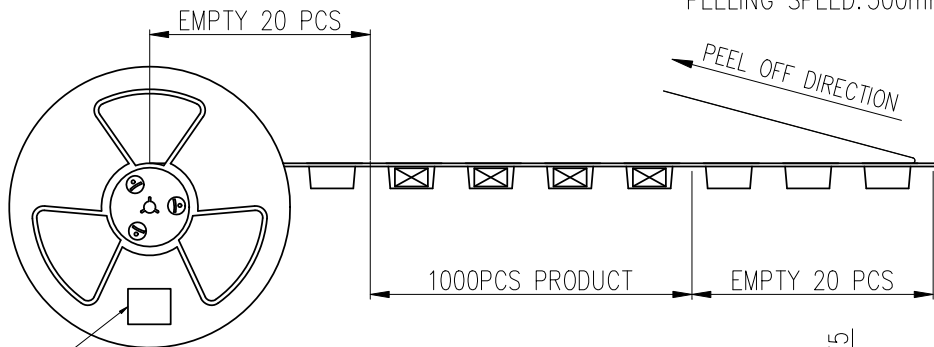
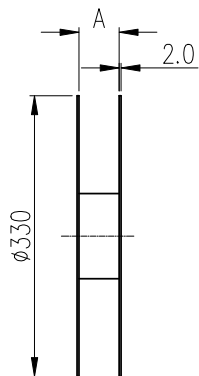
POS	A	B	C	D
2	4.25		3.05	7.25
3	5.50	2.50	4.30	8.50
4	6.75	3.75	5.55	9.75
5	8.00	5.00	6.80	11.00
6	9.25	6.25	8.05	12.25
7	10.50	7.50	9.30	13.50
8	11.75	8.75	10.55	14.75
9	13.00	10.00	11.80	16.00
10	14.25	11.25	13.05	17.25



A		NEW RELEASE	Rock	2018.08.02
REV.	ECN NO	REVISION RECORD	DRAW	DATE

TOLERANCE X. XXX ±0.10 X.X ±0.30 X.XX ±0.20 Angular ±2° UNIT: mm DWG TYPE: Customer Drawing		PART NO. 1253WD-XP-XX-HC-HF		朝貴電子股份有限公司 CKM ELECTRONICS CO., LTD.	
DRAWING NO. C-1253WD-XP-XX-HC-HF		DESCRIPTION 1.25mm PITCH V/T SMT TYPE WAFER			
APPROVED BY Angus.Chen 2018.08.02	CHECKED BY Jeff.Wen 2018.08.02	DRAWN BY Rock 2018.08.02	PAGE 1 OF 2 SCALE 4 : 1	REV. A	

RoHS



LABLE
STICK TO
THE BACK

TABLE 2:

POS	PCS/REEL	PCS/CARTON	NET WEIGHT (KG)	CROSS WEIGHT (KG)
2	1000	3000	0.46	2.58
3	1000	3000	0.53	2.65
4	1000	3000	0.59	2.71
5	1000	3000	0.66	2.78
6	1000	3000	0.73	2.85
7	1000	3000	0.79	2.91
8	1000	3000	0.86	2.98
9	1000	3000	0.92	3.74
10	1000	3000	0.99	3.81

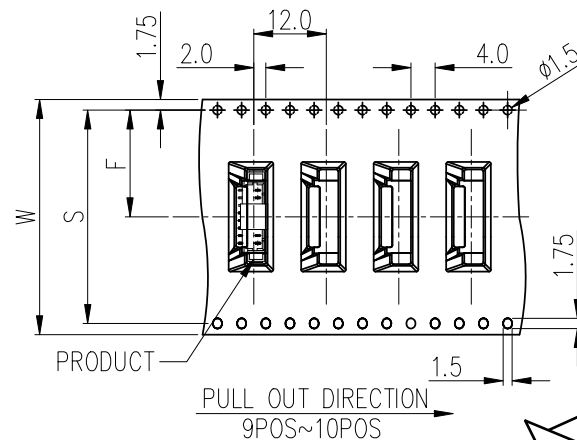
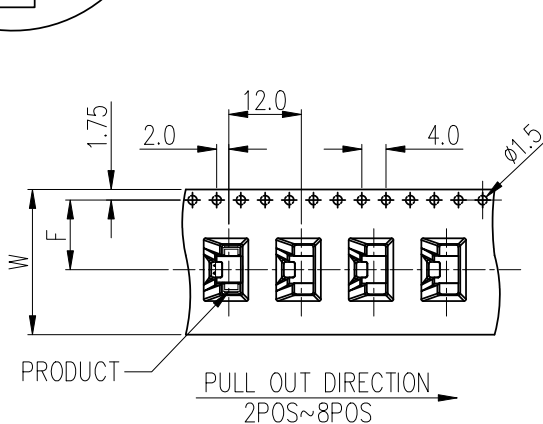
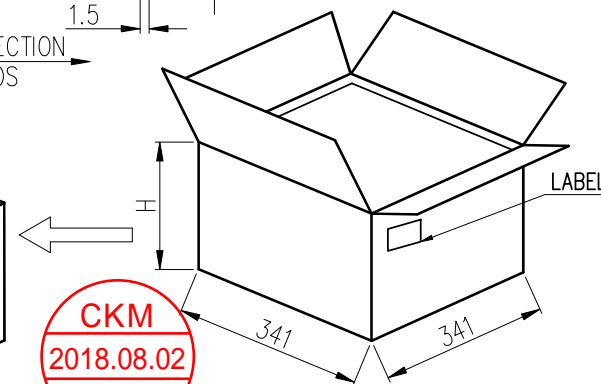
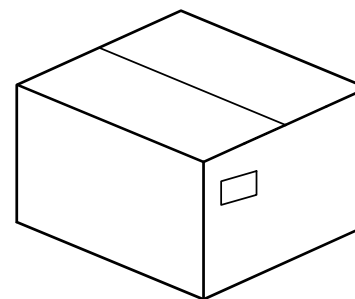


TABLE 1:

POS.	A	W	S	F	H
2~8	24.5	24.0		11.5	120
9~10	44.5	44.0	40.4	20.2	180



CKM
2018.08.02
研发部

TOLERANCE X. X.XXX ±0.10 X.X ±0.30 X.XX ±0.20 Angular ±2°		PART NO. 1253WD-XP-XX-HC-HF		朝貴電子股份有限公司 CKM ELECTRONICS CO., LTD.	
UNIT: mm DWG TYPE. Customer Drawing		DRAWING NO. C-1253WD-XP-XX-HC-HF		DESCRIPTION 1.25mm PITCH V/T SMT TYPE WAFER PACKING	
APPROVED BY Angus.Chen 2018.08.02		CHECKED BY Jeff.Wen 2018.08.02		DRAWN BY Rock 2018.08.02	
REV. A		SCALE 4:1		PAGE 2 OF 2 REV. A	

A		NEW RELEASE	Rock	2018.08.02
REV.	ECN NO	REVISION RECORD	DRAW	DATE